



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



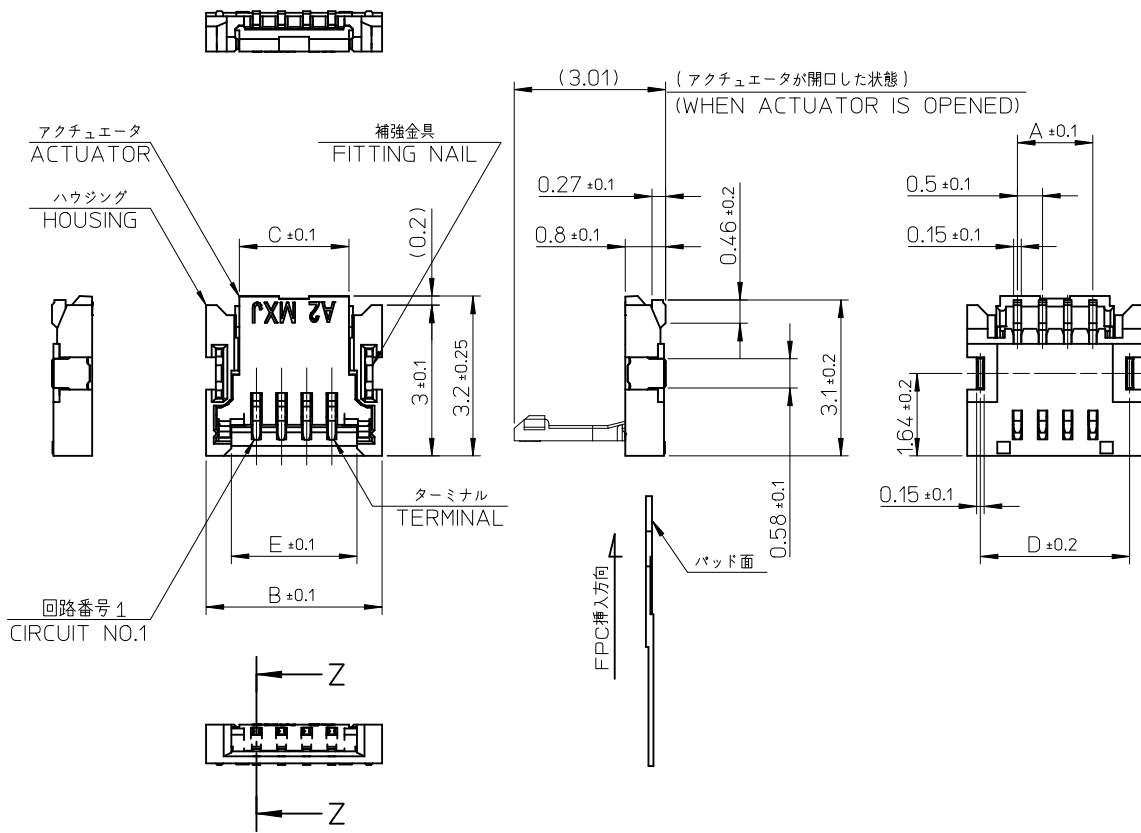
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

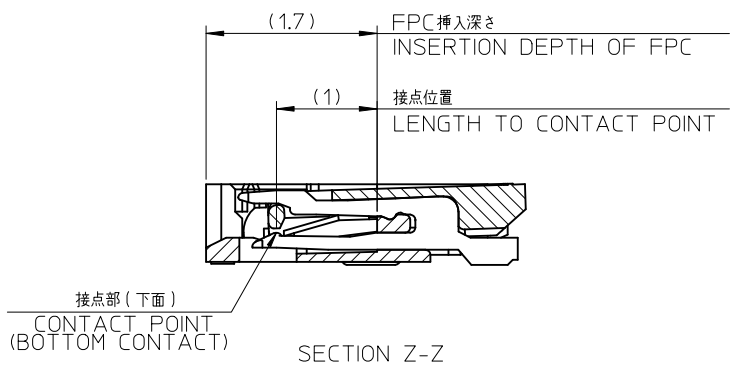
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





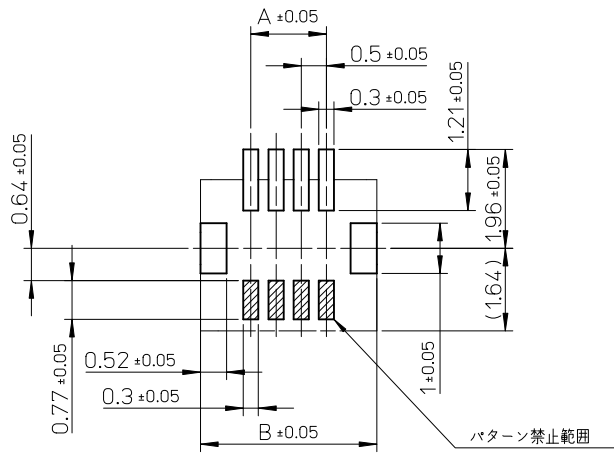
注記
NOTES:

- 1.材質
MATERIAL
ハウジング:耐熱性樹脂、ガラス充填、UL94HB、難燃剤使用
HOUSING:HEAT RESISTANCE POLYMER, GLASS FILLED, UL94HB
FLAME RETARDANTS FREE
アクチュエータ:耐熱性樹脂、ガラス充填、UL94HB、難燃剤使用
ACTUATOR:HEAT RESISTANCE POLYMER, GLASS FILLED, UL94HB
FLAME RETARDANTS FREE
ターミナル:銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
補強金具:銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- 2.めっき仕様
PLATING
ターミナル: 部分金メッキ
接点部 0.1マイクロメートル以上
半田付け部 0.05マイクロメートル以上
TERMINAL: SEPARATED GOLD PLATING
CONTACT AREA 0.1 MICROMETER MINIMUM.
SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
補強金具: 錫メッキ 1.0マイクロメートル以上
NAIL: TIN PLATING 1.0 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
- 3.平坦度は、0.1mm以下とする。
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.
- 4.ELV AND RoHS COMPLIANT.

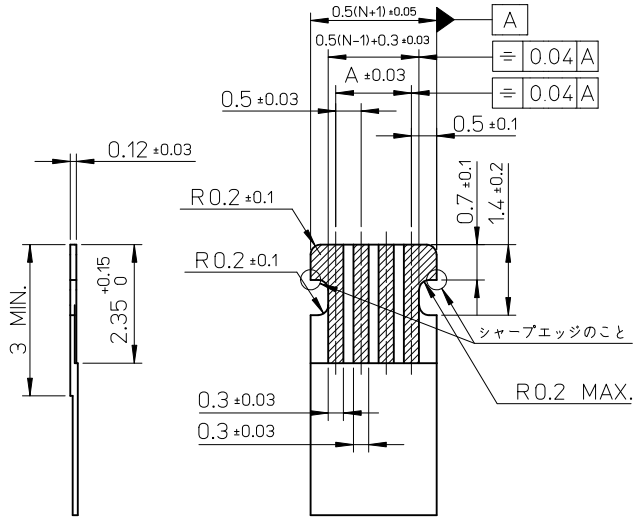


4.5	4.97	4.18	5.5	3.5	501461-0812	501461-0818	8
E	D	C	B	A	エンボス梱包品 EMBOSSED PACKAGING	製品番号 MATERIAL NO.	極数(N) CIRCUITS(N)

RELEASED EC NO: J2011-0733 DRWN: AISHI 2010/11/29 CHKD: TAKAHASHI 2010/11/29 APPR: KMORIKAWA 2010/12/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AISHI		TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY		
	10 OVER 30 UNDER	±0.25	CHECKED BY TAKAHASHI		MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA		DOCUMENT NO. SD-501461-007		
A	REV	ANGULAR ±1°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SHEET NO. 1 OF 2
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



推奨基板寸法
RECOMMENDED P.C.BOARD PATTERN LAYOUT

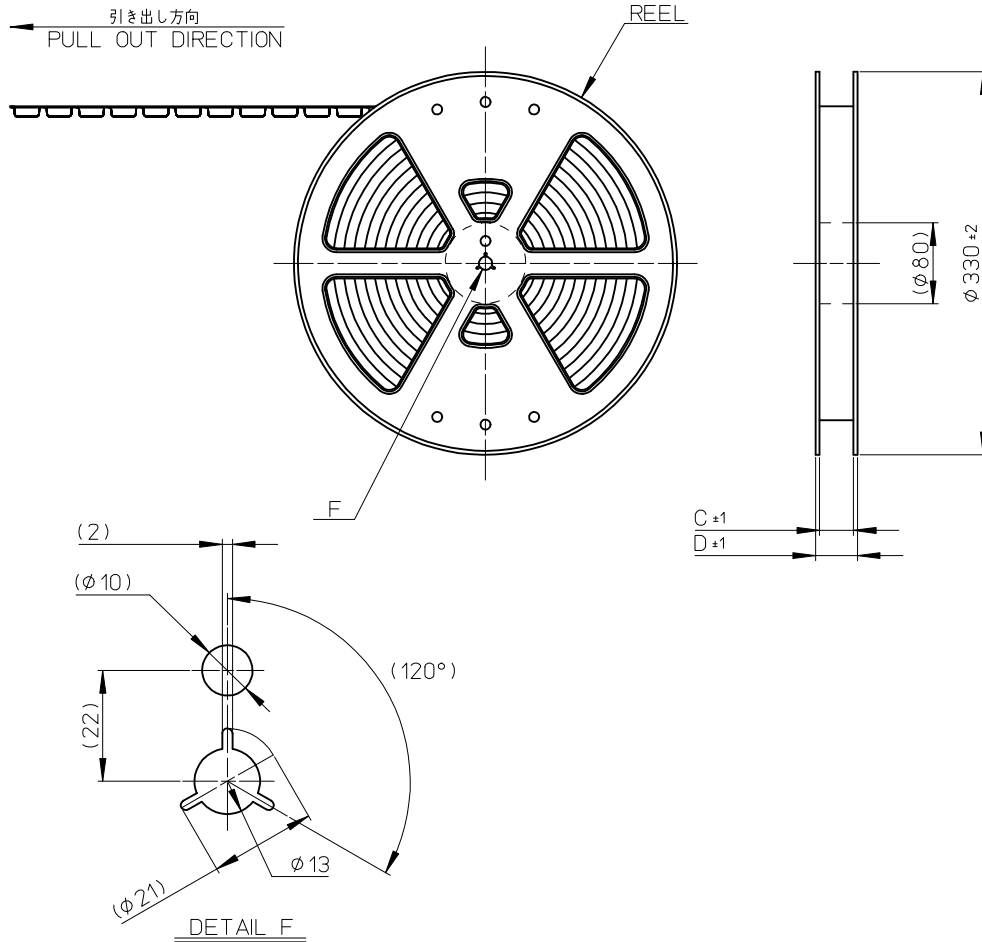


推奨FPC寸法
RECOMMENDED FPC PATTERN LAYOUT

FPCについて：
 抜き方向は、導体側から補強板側を推奨します。
 補強フィルム材質は、ポリイミドを推奨します。
 接着剤は、熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

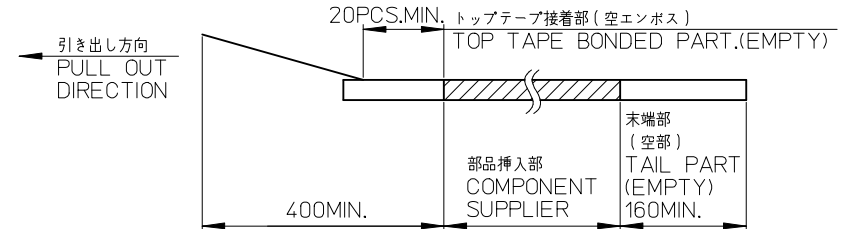
ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFNER FILME SIDE.
 RECOMMENDED MATERIAL:
 STIFFNER FILME: POLYIMIDE
 BONDING AGENT: THRMOSSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

RELEASED EC NO: J2011-0733 DRWN: AISHII 2010/11/29 CHKD: KTAKAHASHI 2010/11/29 APPR: KMORIKAWA 2010/12/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY AISHII	DATE 2010/11/29	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY			
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2010/11/29	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/12/01				
	ANGULAR	±1 °	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-501461-007	SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



NOTES

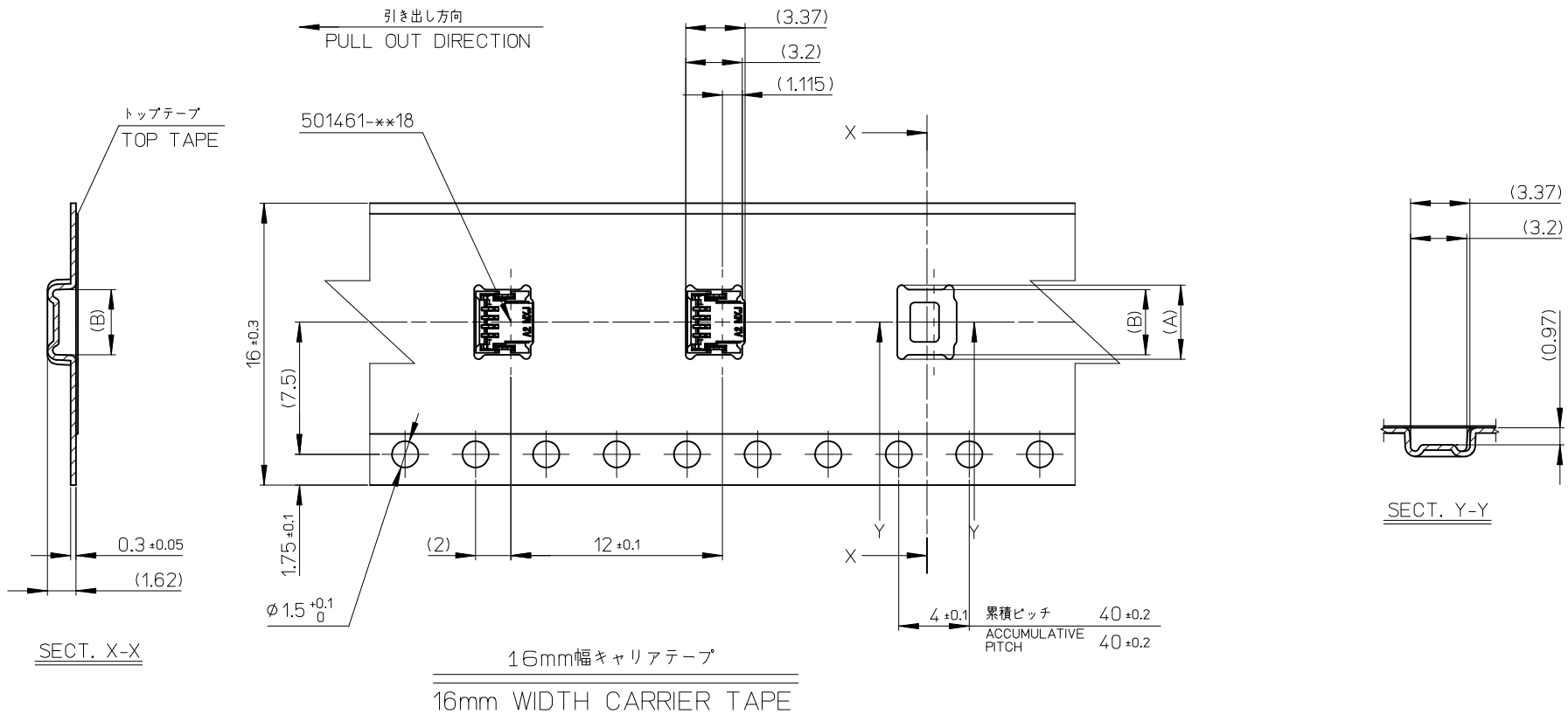
- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS 3000PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ(CARRIRE TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ(TOP TAPE) : PET, PE, PEF
リール(REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAIED>
- ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

REVISED EC NO: J2013-1055 DRWN:SANUMA 2013/03/26 CHKD:KAKAHASHI 2013/03/26 APPR:KMORIKAWA 2013/04/03	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	501461-**12	MODEL NO.	
		10 UNDER ±0.2		DRAWN BY DATE AISHII 2010/11/29		TITLE	0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG		
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE KTAKAHASHI 2010/11/29					
		30 OVER ±0.3		APPROVED BY DATE KMORIKAWA 2010/12/01					
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-501461-008		SHEET NO. 1 OF 2	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10 9 8 7 6 5 4 3 2 1



16	21.4	17.4	5.7	6.2	501461-0812	8
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUITS

SEE SHEET 1 EC NO: J2013-1055 DRWN:NASUNUMA 2013/03/26 CHKD:KATAHASHI 2013/03/26 APPR:KMORIKAWA 2013/04/03	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY AISHII	DATE 2010/11/29	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG		
	10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2010/11/29	molex DOCUMENT NO. SD-501461-008 SHEET NO. 2 OF 2		
	30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2010/12/01			
ANGULAR	± 1 °	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					

9 8 7 6 5 4 3 2